Singulator® MDS-300 bridge tool development supported by EU and SwedenPublic Authorities through EuroPAT MASIP project

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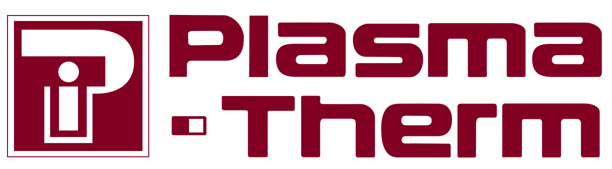

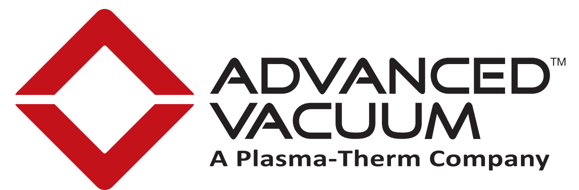

EU Project EuroPAT-MASIP

EuroPAT MASiP

The "**European Packaging, Assembly and Test Pilot for Manufacturing of Advanced System-in-Package**" project will consolidate and extend the European leadership in semiconductor processing know-how and contribute towards keeping Europe at the forefront of the electronics technology development.

Key Challenges

- More than 90 % of the semiconductor packaging, assembly and testing are outside the European value chain, in APAC.
- The increasing complexity of electronic systems, and the trend to System-in-Package (e.g. for IoT modules) solutions, present the chance to increase high added value advanced packaging manufacturing in Europe.
- Semiconductor packaging needs continuous improvement of the three critical factors in packaging - performance, form factor and cost.

Advanced Vacuum and Plasma-Therm's Role

- Development of Plasma Dicing Bridge Tool: Singulator® MDS-300
- Assessment of performance of MDS equipment
- Demonstration on Application Pilots for Microelectronics, Photonics, the Automotive industry, and other emerging markets.

Project Goals and Results

- Increasing the competitiveness and global market share of the European semiconductor industry.
- Accelerating the manufacturing uptake of the new technologies and shortening time-to-market.
- The project will reinforce smart, sustainable economic growth for Europe, significantly contributing to Europe's competitiveness, and job creation in Europe.

Key Project Characteristics

- The total project budget is about 30 M€, including 7,2 M€ from Horizon 2020 programme within the "Electronics Components and Systems for European Leadership" (ECSEL) Joint Undertaking and 5,5 M€ from National authorities.
- 28 partners from 9 European countries
- The project ranked in the top 3 of proposals accepted in the call.